

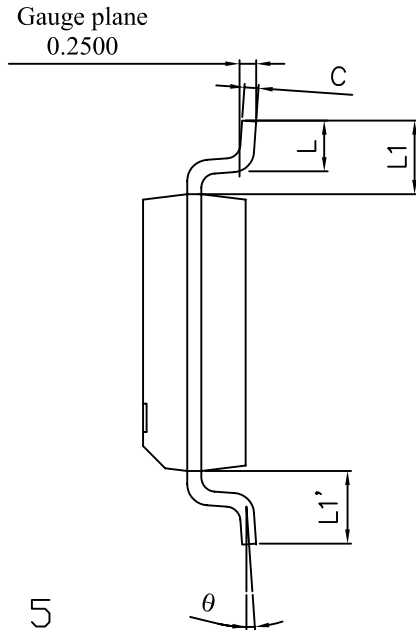
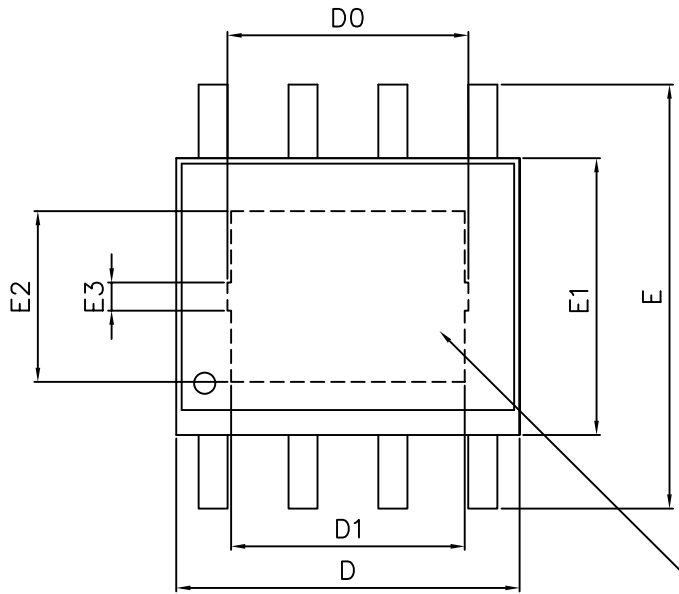


**THE DATASHEET OF
AOZ1053PI**

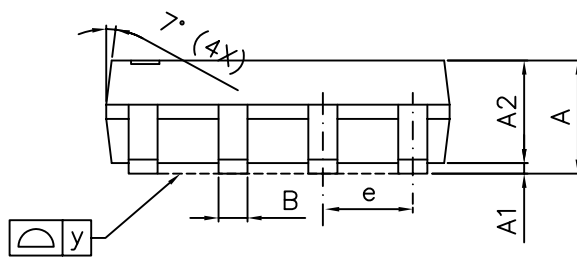




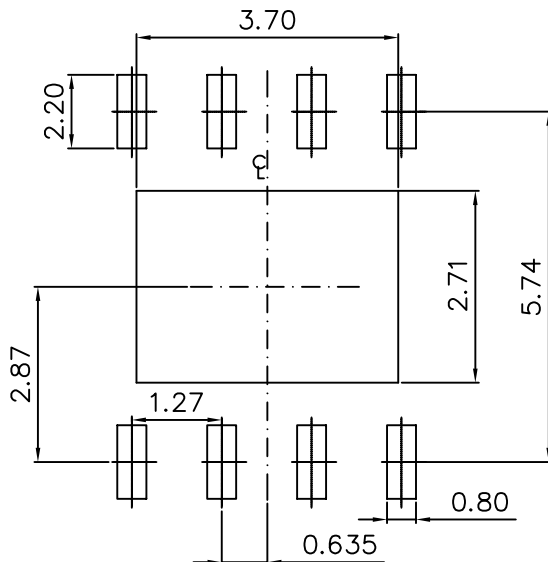
S08_EP1 PACKAGE OUTLINE



NOTE 5



RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.40	1.55	1.70	0.055	0.061	0.067
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	1.40	1.50	1.60	0.055	0.059	0.063
B	0.31	0.406	0.51	0.012	0.016	0.020
C	0.17	—	0.25	0.007	—	0.010
D	4.80	4.96	5.00	0.189	0.195	0.197
D0	3.20	3.40	3.60	0.126	0.134	0.142
D1	3.10	3.30	3.50	0.122	0.130	0.138
E	5.80	6.00	6.20	0.228	0.236	0.244
e	—	1.27	—	—	0.050	—
E1	3.80	3.90	4.00	0.150	0.153	0.157
E2	2.21	2.41	2.61	0.087	0.095	0.103
E3	0.40 REF			0.016 REF		
L	0.40	0.95	1.27	0.016	0.037	0.050
y	—	—	0.10	—	—	0.004
θ	0°	3°	8°	0°	3°	8°
[L1-L1']	—	0.04	0.12	—	0.002	0.005
L1	1.04REF			0.041REF		

NOTE

UNIT: mm

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS
2. DIMENSION L IS MEASURED IN GAGE PLANE
3. TOLERANCE 0.10 mm UNLESS OTHERWISE SPECIFIED
4. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
5. DIE PAD EXPOSURE SIZE IS ACCORDING TO LEAD FRAME DESIGN.
6. FOLLOWED FROM JEDEC MS-012

Looking for pricing, stock, or lifecycle information?

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- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management